

New Organic Conductive Paste with High Electrical Conductivity for Solder Substitution

Strong Points

- 1) The Highest Level of Thermal Conductivity as Organic Paste (10W/mK)
- 2) Good Reflow Performance due to Lower Moisture Absorption Resin System (260°C Reflow)

Application

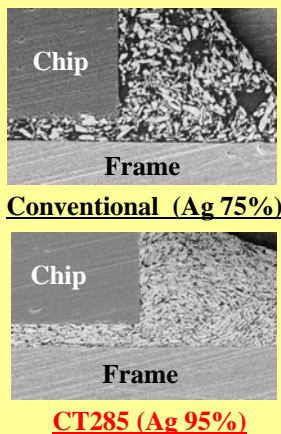
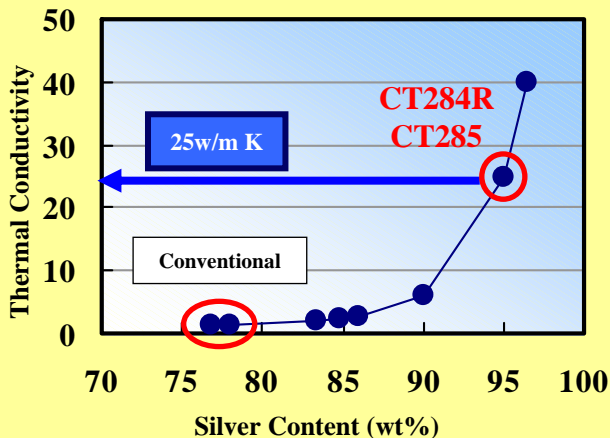
- a) Good for Power IC, Power Transistor, etc.



Characteristic Table of New Silver Paste

Characteristic Item		CT284R	Test Condition
Liquid Properties	Viscosity(Pa s)	105	0.5rpm/25°C
	Tixotropic	6.0	0.5/5.0rpm
	Ash content(wt%)	81.0	600°C
Cured Properties	Ash content(wt%)	95.0	600°C
	Volume Resistance (ohm cm)	6*10 ⁻⁶	25°C
	Tg(°C)	180	TMA
	Modulus(GPa)	6.2	DMA
	CTE(ppm)	48	TMA
	Impurity(ppm)	2.0	Cl ion
	Impurity(ppm)	1.2	Na ion

High Thermal Conductivity by High Loaded Silver Filler



When silver powder is simply filled high, work is bad.

Test	Conventional	CT284R/CT285
Breed Test	Breed (NG)	Good (OK)
Dispense Test 10,000 Shot	Tailing (NG)	Good (OK)

CT284R CT285
Good dispensability